

Hideki Hirano

List of Publications by Year in descending order

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Version: 2024-02-01

22
papers

400
citations

840776

11
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752698

20
g-index

22
all docs

22
docs citations

22
times ranked

306
citing authors

#	ARTICLE	IF	CITATIONS
1	Phonon dispersion in monolayer graphite formed on Ni(111) and Ni(001). Surface Science, 1990, 237, 194-202.	1.9	99
2	Formation of a hybrid surface of carbide and graphite layers on Ni(100) but no hybrid surface on Ni(111). Surface Science, 1989, 222, L809-L817.	1.9	53
3	Dynamic behavior of a Pt _{0.25} Rh _{0.75} (100) single crystal surface during NO + H ₂ reaction. Surface Science, 1990, 226, 1-14.	1.9	42
4	A reason for the structure-insensitive catalytic activity of Ni(100) and Ni(111) surfaces for the methanation reaction of CO. Journal of Catalysis, 1992, 133, 461-466.	6.2	30
5	Off-normal emission of N ₂ produced by desorption mediated reaction of NO on Pd(110) surface. Surface Science, 1994, 315, L973-L976.	1.9	28
6	Integrated 3-axis tactile sensor using quad-seesaw-electrode structure on platform LSI with through silicon vias. Sensors and Actuators A: Physical, 2018, 273, 30-41.	4.1	24
7	Formation of a c(2 × 2) overlayer of nitrogen on Pd(100) by NO + CO reaction or NO + H ₂ reaction. Surface Science, 1990, 231, 304-314.	1.9	22
8	Moving Tunable Filters Forward: A "Heterointegration" Research Project for Tunable Filters Combining MEMS and RF SAW/BAW Technologies. IEEE Microwave Magazine, 2015, 16, 89-97.	0.8	20
9	Low-temperature hermetic thermo-compression bonding using electroplated copper sealing frame planarized by fly-cutting for wafer-level MEMS packaging. Sensors and Actuators A: Physical, 2018, 279, 671-679.	4.1	18
10	Wideband tunable Love wave filter using electrostatically actuated MEMS variable capacitors integrated on lithium niobate. Sensors and Actuators A: Physical, 2012, 188, 456-462.	4.1	12
11	Environmentally Benign Single-Wafer Spin Cleaning Using Ultra-Diluted HF/Nitrogen Jet Spray Without Causing Structural Damage and Material Loss. IEEE Transactions on Semiconductor Manufacturing, 2007, 20, 252-258.	1.7	11
12	Wafer-level vacuum sealing using AgAg thermocompression bonding after fly-cut planarization. Sensors and Actuators A: Physical, 2017, 261, 210-218.	4.1	8
13	Event-Driven Tactile Sensing System Including 100 CMOS-MEMS Integrated 3-Axis Force Sensors Based on Asynchronous Serial Bus Communication. IEEE Sensors Journal, 2020, 20, 10159-10169.	4.7	6
14	Isolation of intermediate compounds of catalytic reactions on single crystal surfaces. Catalysis Letters, 1992, 12, 1-6.	2.6	5
15	Zero-Balance Method for Evaluation of Sealed Cavity Pressure Down to Single Digit Pa Using Thin Silicon Diaphragm. Journal of Microelectromechanical Systems, 2020, 29, 418-426.	2.5	5
16	Development of a Real-Time Force and Temperature Sensing System with MEMS-LSI Integrated Tactile Sensors for Next-Generation Robots. Journal of Robotics and Mechatronics, 2020, 32, 323-332.	1.0	5
17	Particle Removal without Causing Damage to MEMS Structure. IEJ Transactions on Sensors and Micromachines, 2013, 133, 157-163.	0.1	4
18	Metal-bonding-based hermetic wafer-level MEMS packaging technology using in-plane feedthrough: Hermeticity and high frequency characteristics of thick gold film feedthrough. Electrical Engineering in Japan (English Translation of Denki Gakkai Ronbunshi), 2019, 206, 44-53.	0.4	2

#	ARTICLE	IF	CITATIONS
19	Tactile Sensing System Module with Multiple Cmos-Mems Integrated Sensors on 16 Mbps High Speed Shared Serial Bus Line. , 2019, , .		2
20	Wafer-level High Vacuum Packaging using Titanium Thin Film as Bonding and Gettering Material. IEEJ Transactions on Sensors and Micromachines, 2018, 138, 387-391.	0.1	2
21	Dynamical behaviour of Pt-Rh(100) alloy surface during dissociative adsorption of no and reaction of no with H2. Surface Science Letters, 1989, 222, L804-L808.	0.1	1
22	Monolithic Integration of BST Thin Film Varactors and Au Electroplated Thick Film Inductors above IC. IEEJ Transactions on Sensors and Micromachines, 2015, 135, 323-329.	0.1	1